



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): YAZAKI et al.

Atty. Dkt.: 01-244-DIV

Serial No.: 10/643,919

Group Art Unit: 1775

Filed: August 20, 2003

Examiner: Unknown

Title: PRINTED WIRING BOARD AND
METHOD OF MANUFACTURING A
PRINTED WIRING BOARD

Commissioner for Patents
Arlington, VA 22202

Date: December 16, 2003

INFORMATION DISCLOSURE STATEMENT

Sir:

Pursuant to 37 C.F.R. §1.56, the references listed on the attached Form PTO-1449 are being submitted for consideration by the Examiner without any admission that they constitute statutory prior art, or without any admission that they contain subject matter that anticipates the invention or renders the invention obvious to a person of ordinary skill in the art.

Although no fees are believed to be due at this time, it is respectfully requested that any such fees be charged to Deposit Account 50-1147. Also, the Examiner is requested to initial the attached PTO Form-1449 and to return a copy of same to the undersigned attorney as proof that the listed references have been considered and made of record.

Respectfully submitted,

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FORM PTO-1449	ATTY. DKT NO.	01-244-DIV	SER. NO.	10/643,919
	APPLICANT YAZAKI et al.			
	FILING DATE	August 20, 2003	GROUP	1775

REFERENCE DESIGNATION

U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS
	4,435,611	Mar. 6, 1984	Ohsawa et al.		
	5,031,308	Jul. 16, 1991	Yamashita et al.		
	5,573,622	Nov. 12, 1996	Hass et al.		
	5,906,042	May 25, 1999	Lan et al.		
	5,972,482	Oct. 26, 1999	Hatakeyama et al.		
	6,000,129	Dec. 14, 1999	Bhatt et al.		
	5,439,164	Aug. 8, 1995	Hasegawa et al.		
	5,551,626	Sep. 3, 1996	Hasegawa et al.		

FOREIGN PATENT DOCUMENTS

								TRANSLATION	
		DOCUMENT NUMBER	DATE	COUNTRY	NAME	CLASS	SUB CLASS	YES	NO

* Full English text of the JP Document will be available in machine-translated form from JP (Japanese Patent Office) English language web site at <http://www1.ipdl.jpo.go.jp/PA1/cgi-bin/PA1INDEX>.

OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, etc.)

	S.K. Kang et al. "Development of Conductive Adhesive Materials for Via Fill Applications", 2000 Electronic Components and Technology Conference, 2000, pp.887-891
EXAMINER	DATE CONSIDERED

